

Dwight Look College of
ENGINEERING
TEXAS A&M UNIVERSITY

Schematic Capture PCB Design Assembly Tips

Dr. John Lusher II, P.E.

Outline

- PCB Design Process
- Recommended Software
- Common Mistakes
- Assembly Tips
- Debugging PCBs and Systems

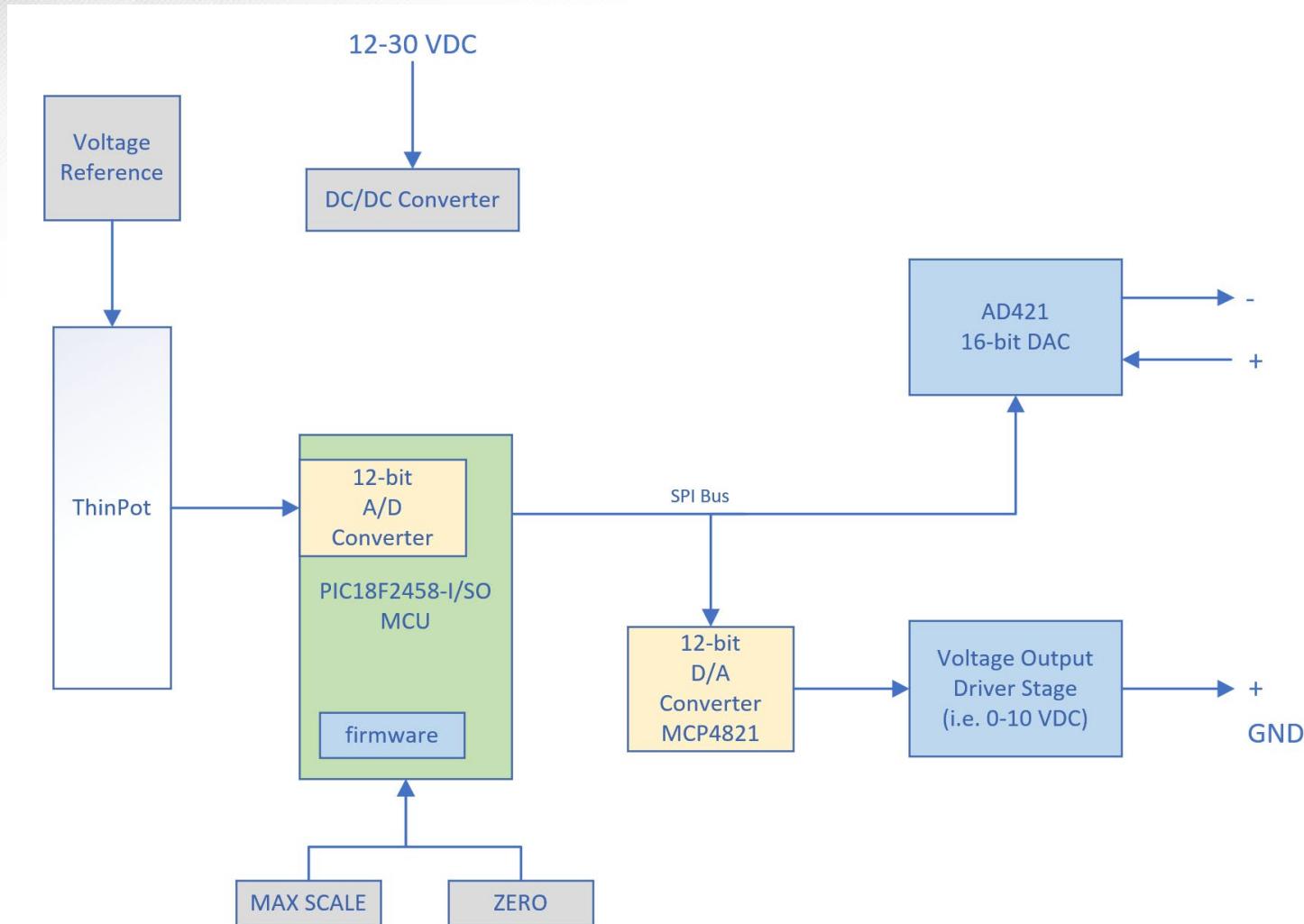
Process of PCB Design

1. Capture the schematic for the PCB
2. Produce a netlist
3. Place and Route the PCB
4. Verify PCB meets manufacturing rules
5. Produce CAM files for manufacturing

Schematic Capture

- Start with block diagram of system
- **Select all parts FIRST!**
 - This includes resistors, capacitors, ICs, etc..
- Create or get symbols for the part.
- Design the schematic
- If a complicated board then use a hierachal based design

Schematic Capture: Block Diagram



Schematic Capture: Select Parts

Ceramic Capacitors

Results: 423,529

Search Within Results

Filter Options: **Stacked** **Scrolling**

Manufacturer	Packaging	Series	Part Status
American Technical Ceramics	Bag	AH	Active
AVX Corporation	Bulk	APS	Discontinued at Digi-Key
Cornell Dubilier Electronics (CDE)	Cut Tape (CT)	AO	Last Time Buy
Johanson Dielectrics Inc.	Digi-Reel®	ARA Indust X7R HT200C	Not For New Designs
Johanson Technology Inc.	Tape & Box (TB)	ArcShield SMD Comm X7R HV	Obsolete
KEMET	Tape & Reel (TR)	ARR Indust X7R HT200C	Preliminary
Knowles Dielectric Labs	Tray	AS	
Knowles Novacap	Tube	AT	
Knowles Syfer		ATC 100C	
Kyocera International Inc. Electronic Components		ATC-100F	

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View Prices At: Enter Quantity

Stock Status In Stock Normally Stocking New Products Datasheet Photo EDA / CAD Models RoHS Compliant Non-RoHS Compliant

Clear All Selections **Apply Filters**

Search Entry: 0.1 uF Cap

Results per Page: 500 Page 1/848 < 1 2 3 4 5 > >>

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Compare Parts	Image	Digi-Key Part Number	Manufacturer Part Number	Manufacturer	Description	Quantity Available <input type="button"/>	Unit Price USD	Minimum Quantity	Packaging	Series	Part Status	Capacitance
<input type="checkbox"/>		GRM0335C1E101JA01D	Murata Electronics	CAP CER 100PF 25V COG/NP0 0201	1,782,893 Immediate	\$0.00180	15,000	Tape & Reel (TR) <input type="button"/> <small>Alternate Packaging</small>	GRM	Active	100pF	
<input type="checkbox"/>		GRM0335C1E101JA01D	Murata Electronics	CAP CER 100PF 25V COG/NP0 0201	1,782,293 - Immediate	\$0.10000	1	Cut Tape (CT) <input type="button"/> <small>Alternate Packaging</small>	GRM	Active	100pF	
<input type="checkbox"/>		GRM0335C1E101JA01D	Murata	CAP CER 100PF 25V COG/NP0 0201	1,782,793	Digi-Reel®	1	Digi-Reel® <input type="button"/>	GRM	Active	100pF	

Embedded - Microcontrollers

Results: 85,883

Search Within Results

Filter Options: **Stacked** **Scrolling**

Manufacturer	Packaging	Series
Adafruit Industries LLC	Bag	568xx
Ambiq Micro, Inc.	Box	56FB36xx
Analog Devices Inc.	Bulk	56FB37xx
Arduino	Cut Tape (CT)	56FBxx
BridgeTek Pte Ltd.	Digi-Reel®	56FBxxx
Cypress Semiconductor Corp	Strip	720/4500
Epson Electronics America Inc-Semiconductor Div	Tape & Box (TB)	73S11xx
Fujitsu Electronics America, Inc.	Tape & Reel (TR)	73S12xx
Honeywell Aerospace	Tray	
Infineon Technologies		

More Filters

View Prices At: Enter Quantity

Stock Status In Stock Normally Stocking New Products Datasheet Photo EDA / CAD Models RoHS Compliant Non-RoHS Compliant

Clear All Selections **Apply Filters**

Search Entry: Microcontroller

Results per Page: 500 Page 1/172 < 1 2 3 4 5 > >>

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Compare Parts	Image	Digi-Key Part Number	Manufacturer Part Number	Manufacturer	Description	Quantity Available <input type="button"/>	Unit Price USD	Minimum Quantity	Packaging	Series
<input type="checkbox"/>		PIC10F200T-IOTTR-ND	PIC10F200T-IOT	Microchip Technology	IC MCU 8BIT 384B FLASH SOT236	51,000 - Immediate	\$0.38750	3,000	Tape & Reel (TR) <input type="button"/> <small>Alternate Packaging</small>	PIC® 10F
<input type="checkbox"/>		PIC10F200T-IOTCT-ND	PIC10F200T-IOT	Microchip Technology	IC MCU 8BIT 384B FLASH SOT236	53,113 - Immediate	\$0.45000	1	Cut Tape (CT) <input type="button"/> <small>Alternate Packaging</small>	PIC® 10F
<input type="checkbox"/>		PIC10F200T-IOTDKR-ND	PIC10F200T-IOT	Microchip Technology	IC MCU 8BIT 384B FLASH SOT236	53,113 - Immediate	Digi-Reel® <input type="button"/>	1	Digi-Reel® <input type="button"/> <small>Alternate Packaging</small>	PIC® 10F

Schematic Capture: Examine Datasheet



PIC10F200/202/204/206

6-Pin, 8-Bit Flash Microcontrollers

Devices Included In This Data Sheet:

- PIC10F200
- PIC10F204
- PIC10F202
- PIC10F206

High-Performance RISC CPU:

- Only 33 Single-Word Instructions to Learn
- All Single-Cycle Instructions except for Program Branches, which are Two-Cycle
- 12-Bit Wide Instructions
- 2-Level Deep Hardware Stack
- Direct, Indirect and Relative Addressing modes for Data and Instructions
- 8-Bit Wide Data Path
- Eight Special Function Hardware Registers

Low-Power Features/CMOS Technology:

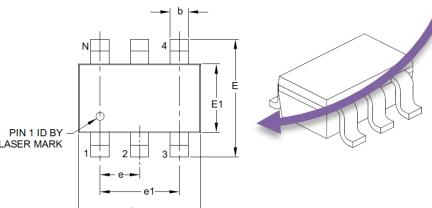
- Operating Current
 - < 175 μ A @ 2V
- Standby Current
 - 100 nA @ 2V
- Low-Power, High Performance
 - 100,000 Flash Erase Cycles
 - > 40 year rete
- Fully Static Design
- Wide Operating Temperature
 - Industrial: -40° to +80°C
 - Extended: -40° to +125°C

14.2 Package Details

The following sections give the technical details of the packages.

6-Lead Plastic Small Outline Transistor (OT) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



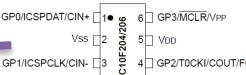
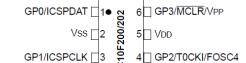
Dimension	Units			Millimeters		
	Number of Pins	Dimension Limits	MIN	NOM	MAX	
Pitch		N	6			
Outside Lead Pitch	e		0.95 BSC	1.90 BSC		
Overall Height	e1					
Molded Package Thickness	A	0.90	—	1.45		
Standoff	A1	0.00	—	0.15		
Overall Width	E	2.20	—	3.20		
Molded Package Width	E1	1.30	—	1.80		
Overall Length	D	2.70	—	3.10		
Foot Length	L	0.10	—	0.60		
Footprint	L1	0.35	—	0.80		
Foot Angle	b	0°	—	30°		
Lead Thickness	c	0.08	—	0.26		
Lead Width	b	0.20	—	0.51		

Notes:

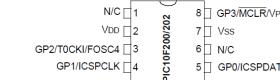
1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
2. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

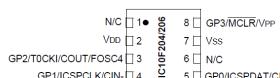
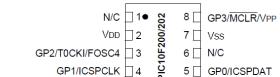
FIGURE 1: 6-PIN SOT-23



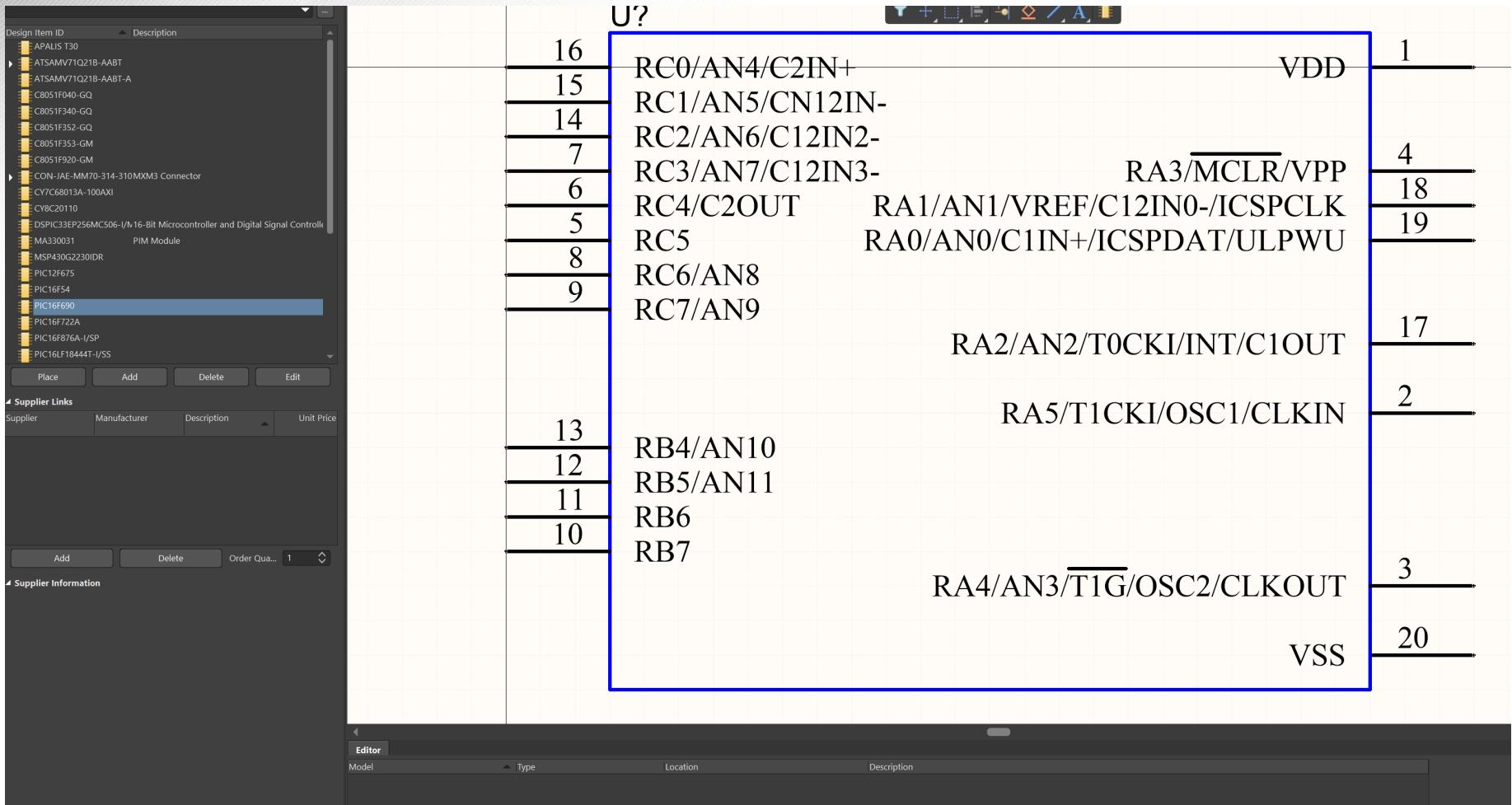
8-PIN PDIP



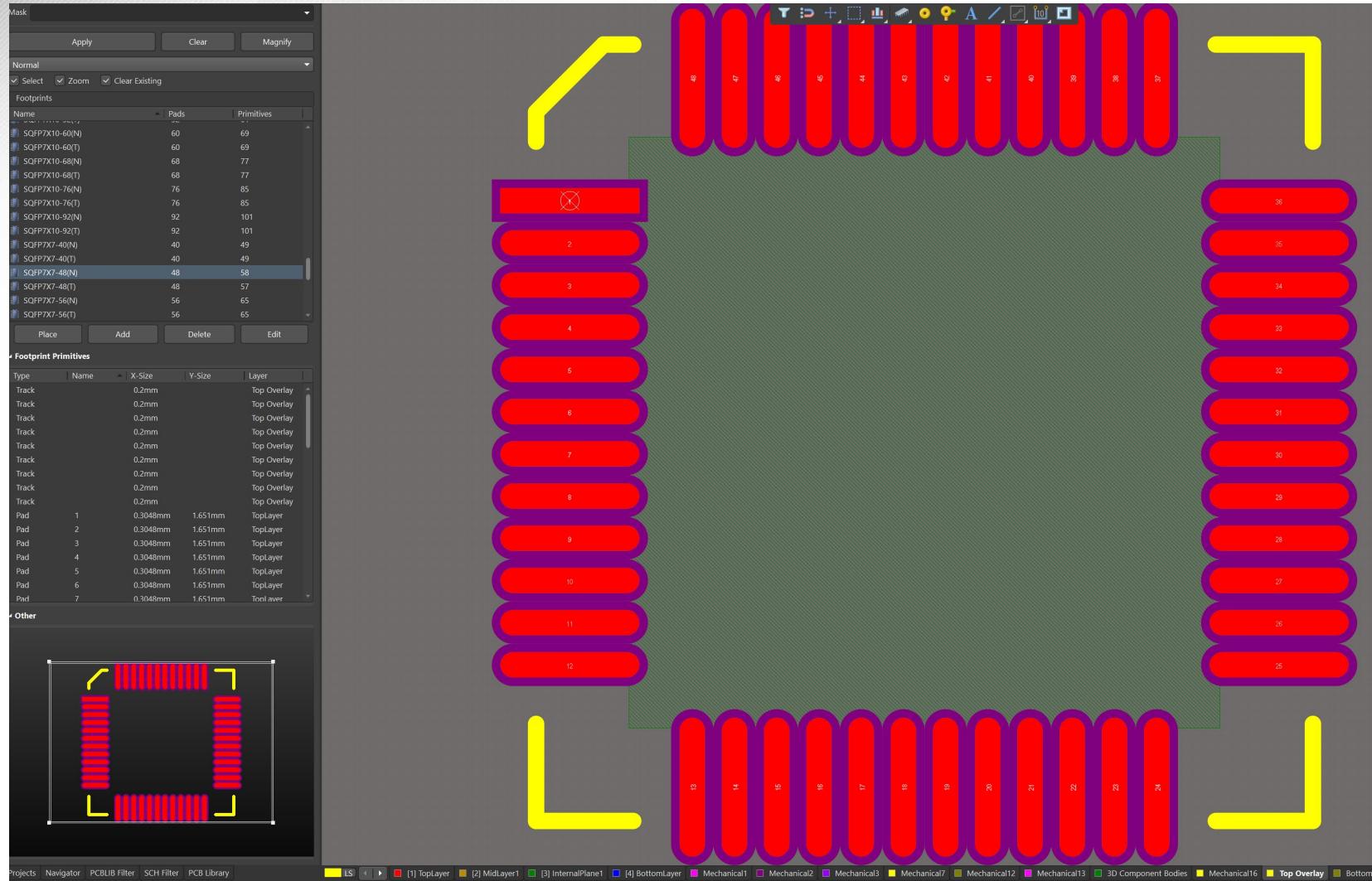
8-PIN DFN



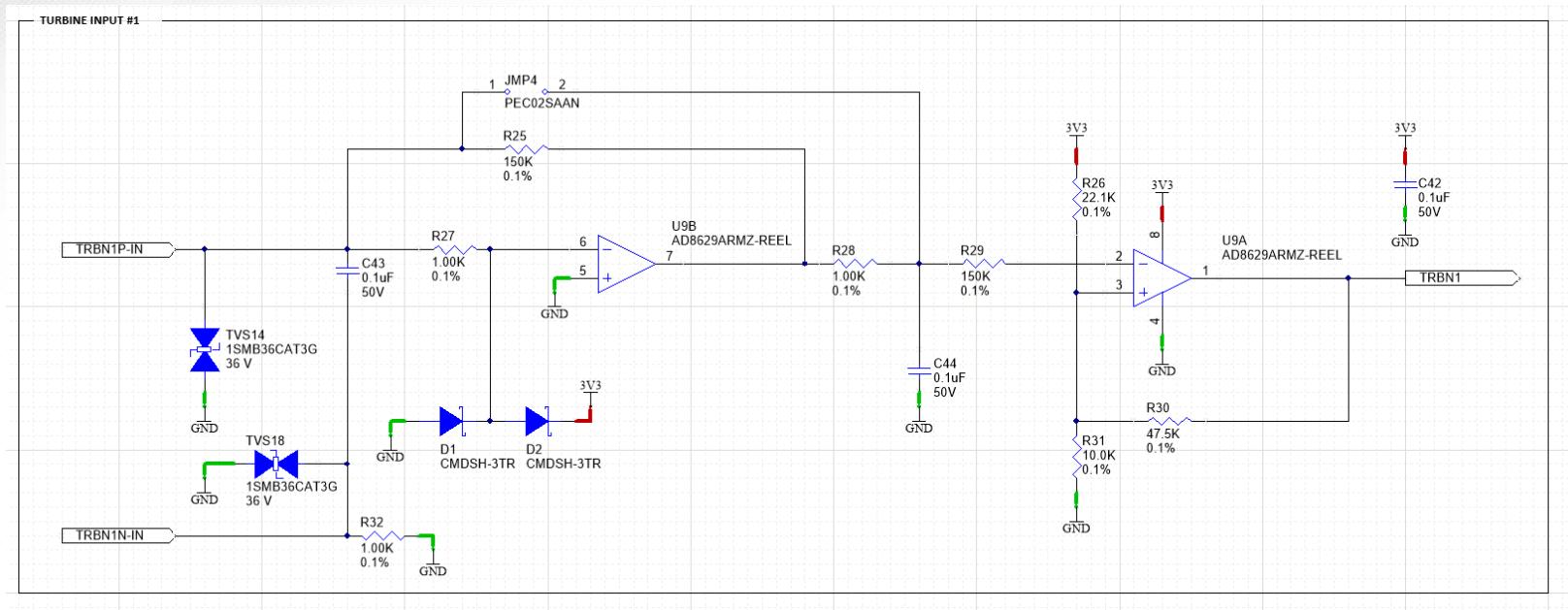
Schematic Capture: Creating Symbols



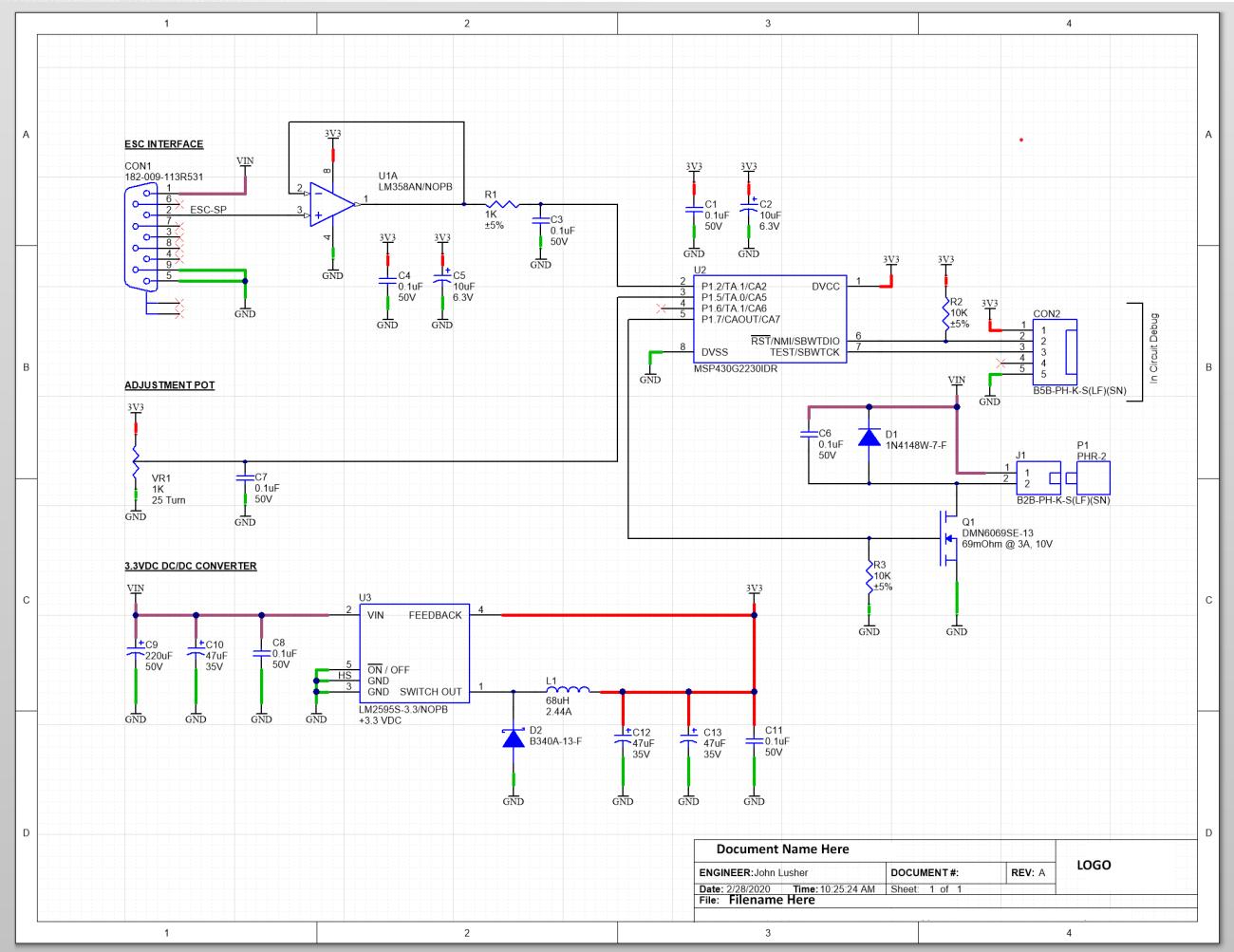
Schematic Capture: Creating Footprints



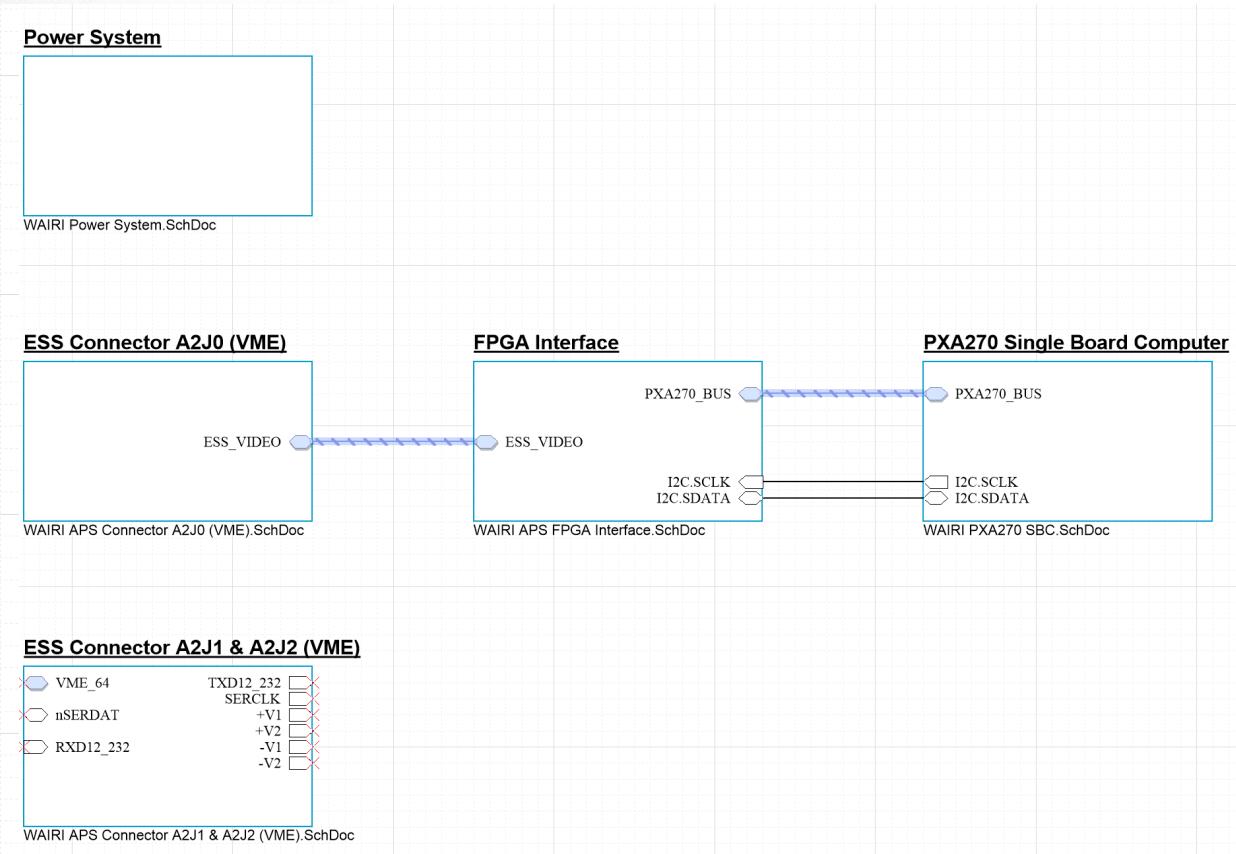
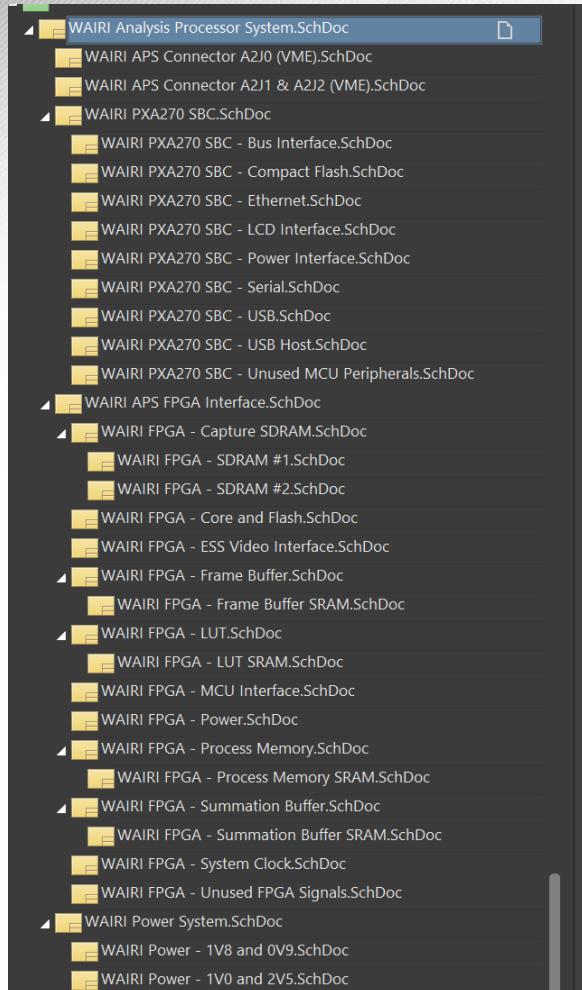
Schematic Capture



Schematic Capture

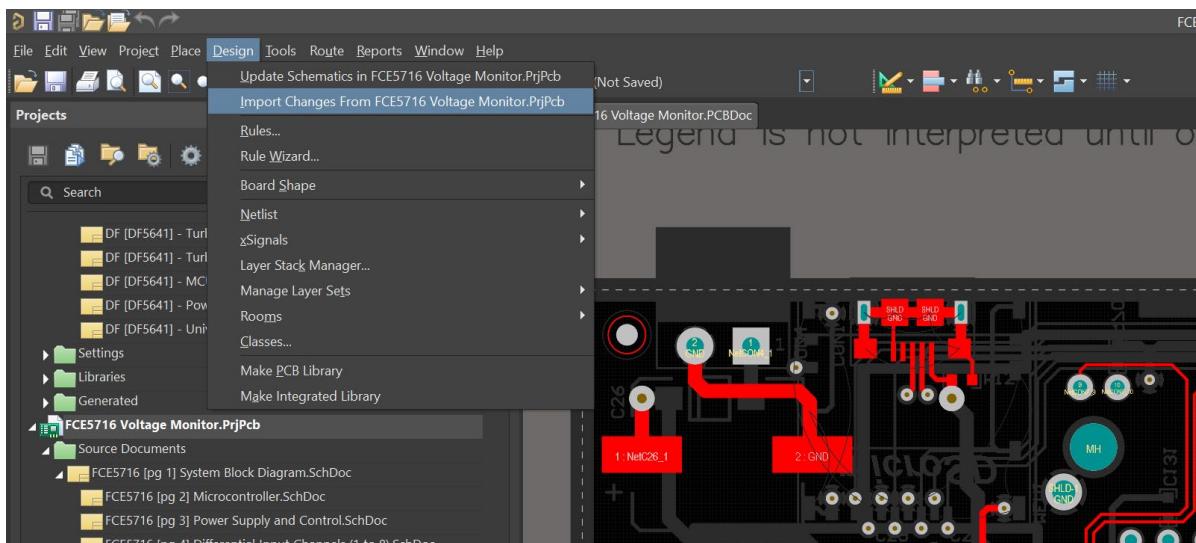


Schematic Capture: Hierarchical Design

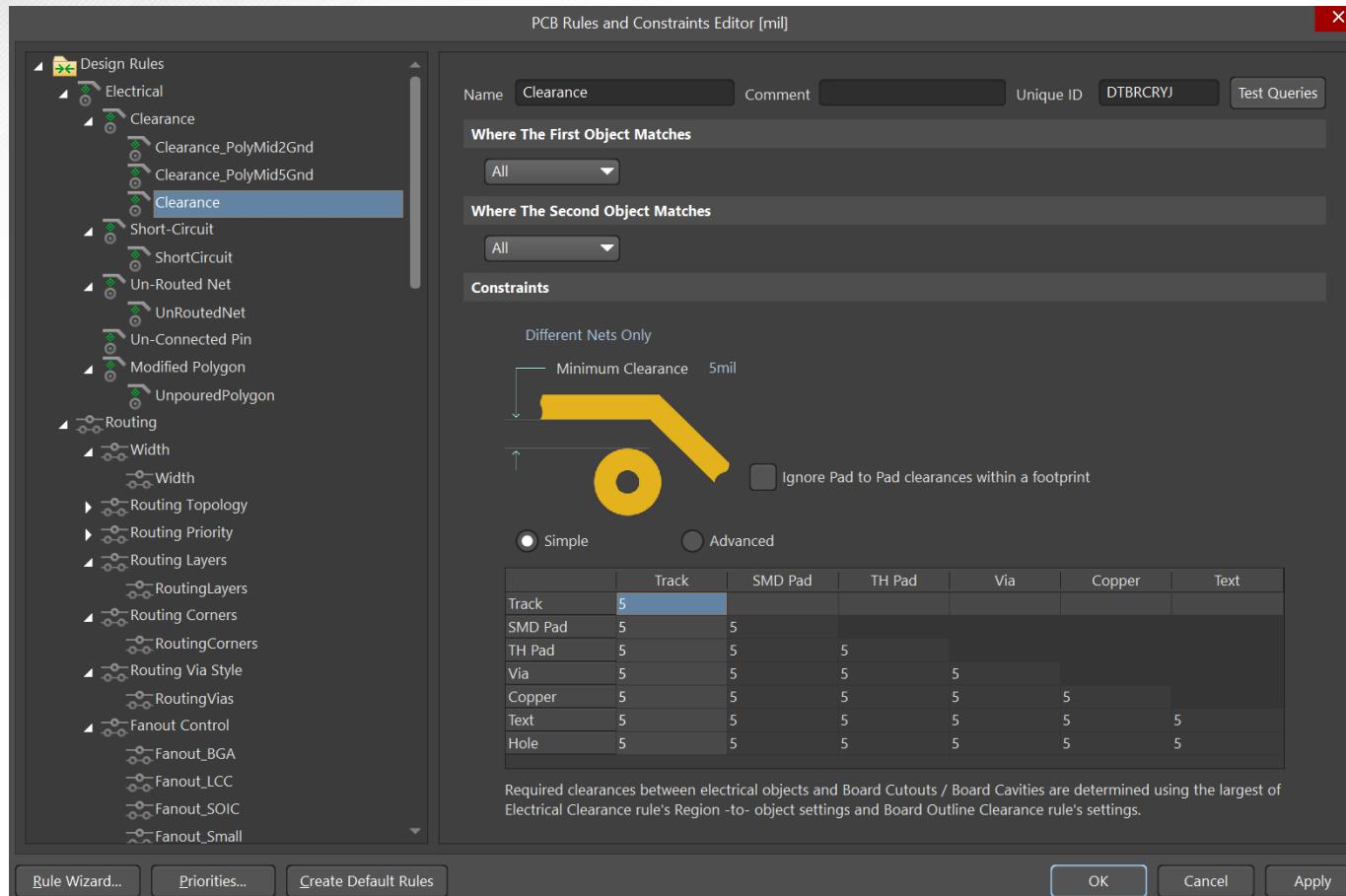


Create A Netlist

- This step may be automatic based upon the software being used.
- Altium “compiles” the schematic and then you import the design into the PCB editor.



PCB Place and Route: Set Design Rules



PCB Place and Route: Placement

- Define board shape and mounting holes. Typically driven by mechanical design constraints.
- Import netlist into PCB design.
- Place components
 - Some parts have required position, like connectors, or due to airflow, etc...
 - Examine your design and group parts together
 - Look at “rats-nest” to place parts that do not have a required placements to balance out the routing.

PCB Place and Route: Routing

- DO NOT USE AUTO-ROUTER!**

- Unless you are good at setting appropriate design rules.
- Trace Size Matters!**
 - Trace width is set by the current being used in the track. There are tools to determine the appropriate track width:
 - <https://www.4pcb.com/trace-width-calculator.html>

Printed Circuit Board Width Tool

This Javascript web calculator calculates the trace width for printed given current using formulas from IPC-2221 (formerly IPC-D-275).

Inputs:

Current	10	Amps
Thickness	2	oz/ft ²

Optional Inputs:

Temperature Rise	10	Deg	C
Ambient Temperature	25	Deg	C
Trace Length	1	inch	

Results for Internal Layers:

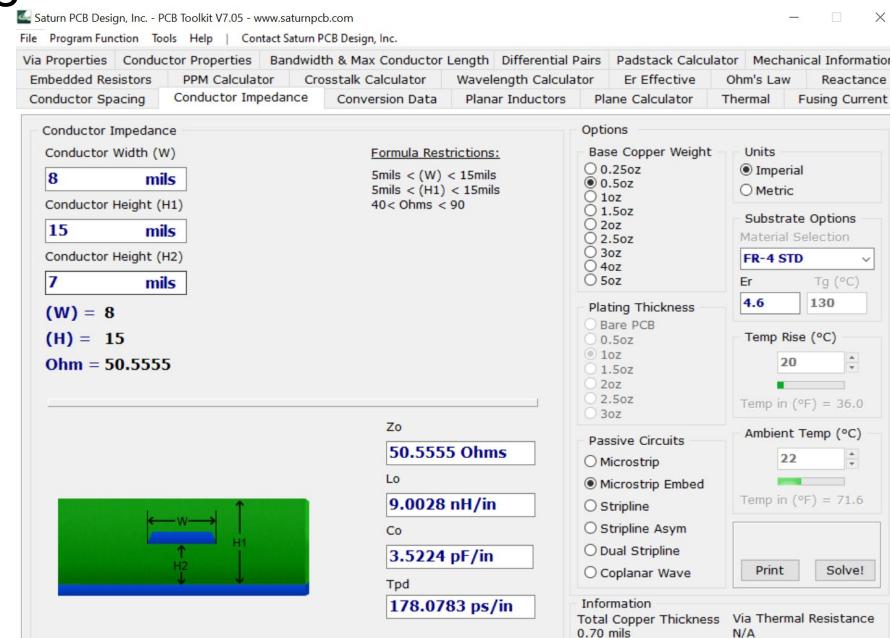
Required Trace Width	368	mil
Resistance	0.000685	Ohms
Voltage Drop	0.00685	Volts
Power Loss	0.0685	Watts

Results for External Layers in Air:

Required Trace Width	142	mil
Resistance	0.00178	Ohms
Voltage Drop	0.0178	Volts
Power Loss	0.178	Watts

PCB Place and Route: Routing

- The layout process will take time! Be Patient!
- Physics matters!
 - Hence, signal speed, voltages, currents, impedance does enter the design. If you have high speed signals you will need to calculate the impedance of a trace and possibly keep signals the same length.

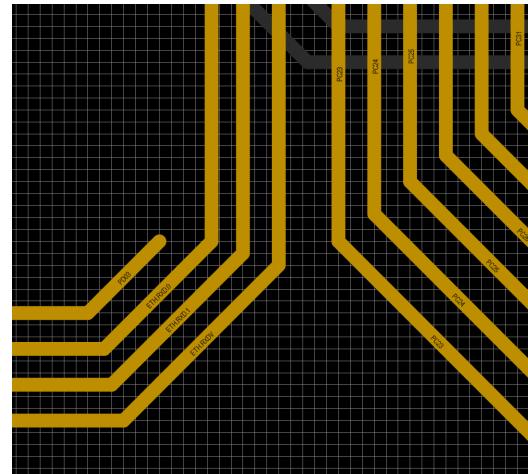


PCB Place and Route: Routing

- Don't use 90 degree turns!



- Instead, use 45 degree turns!



PCB Place and Route: Routing

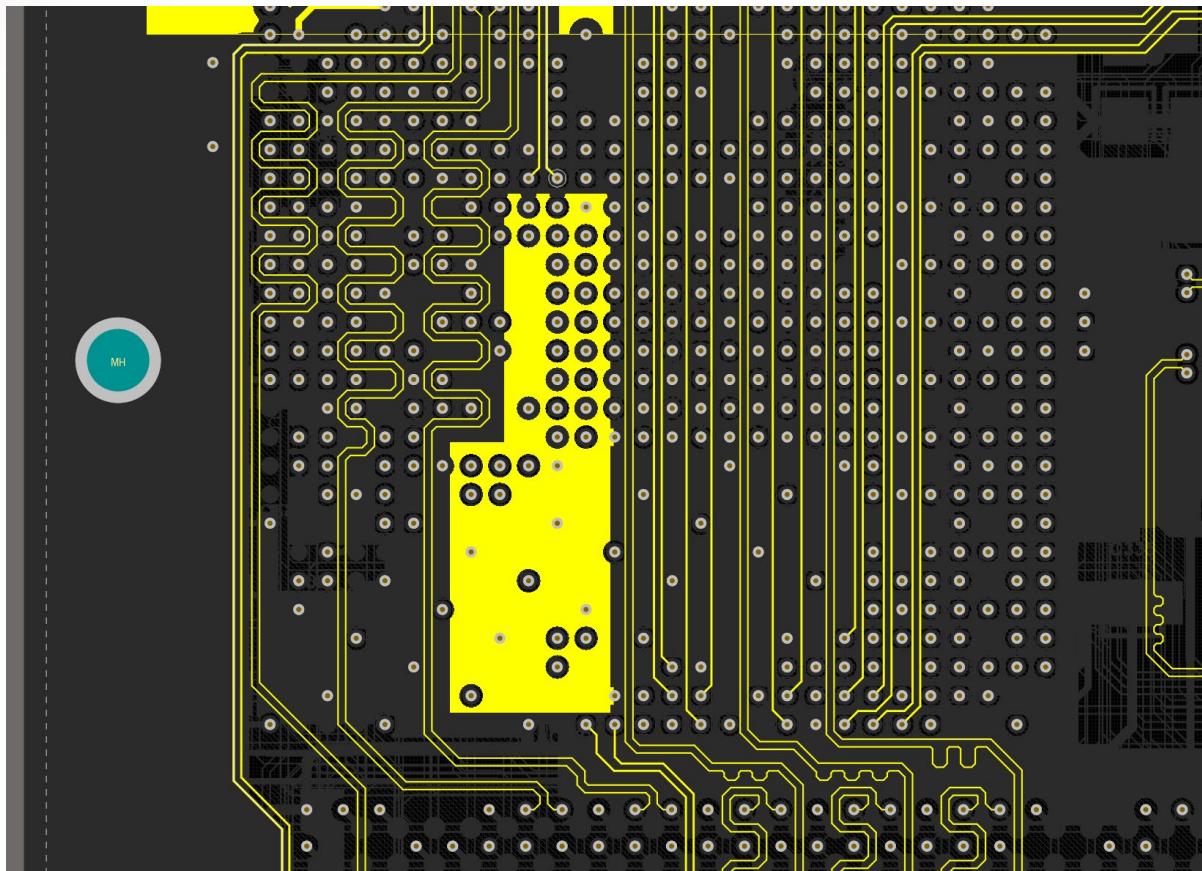
- It is ok to have extra parts on the PCB! Once the shape of the PCB is set, copper is “free.”
- If you are defining the layout of a connector this also means you can change to suit the layout.
- I/O can also be remapped on most MCUs and FPGAs, take. Remap your I/O to make routing the most effective.

PCB Place and Route: Routing

- Don't just pour a ground plane polygon to "reduce noise," because that is what you have seen everyone else do.
- Think of how you will assemble the board when designing.

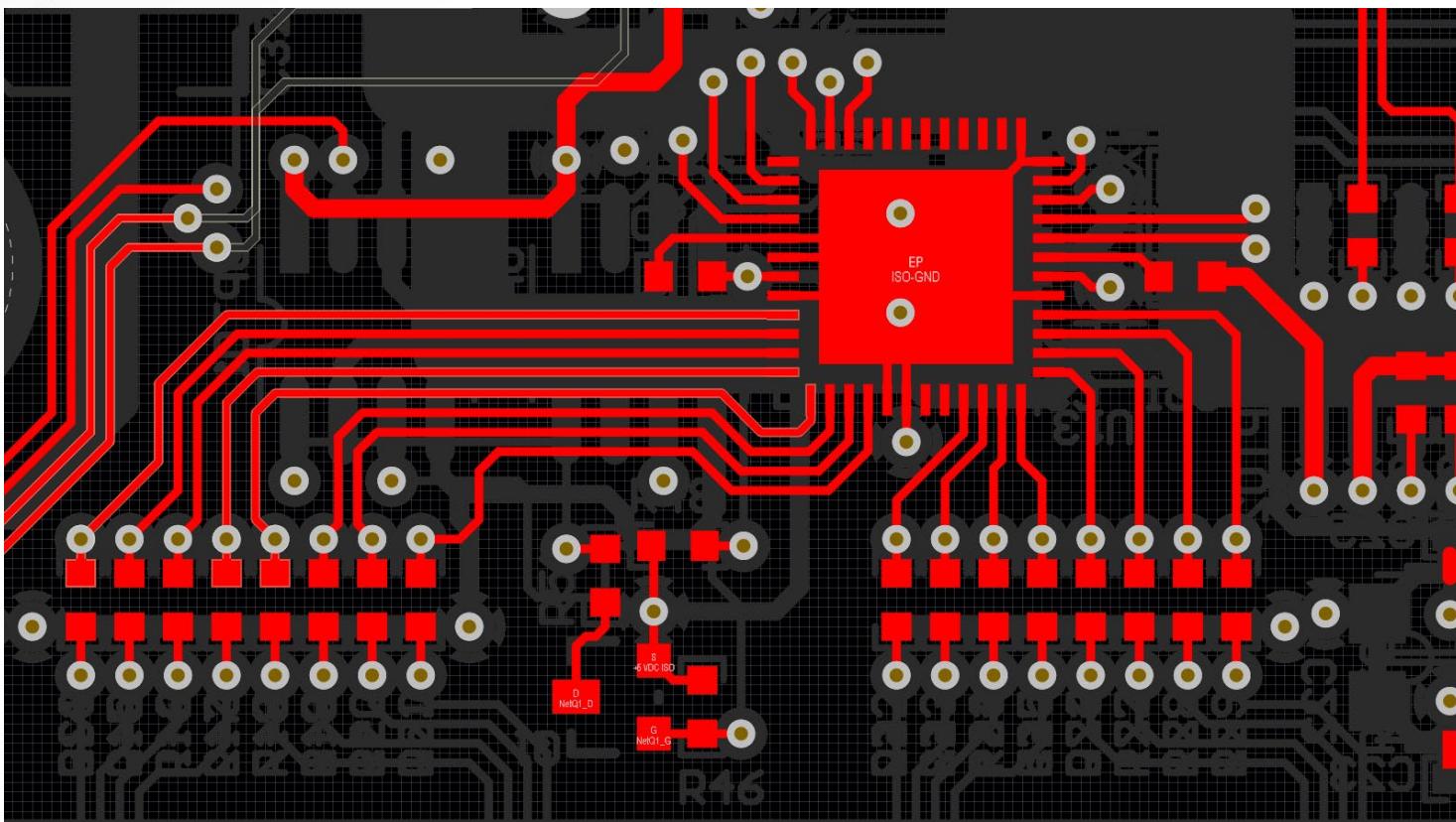
PCB Place and Route: Routing

- Consider track lengths. At high frequency trace length matters and you may have to match lengths!



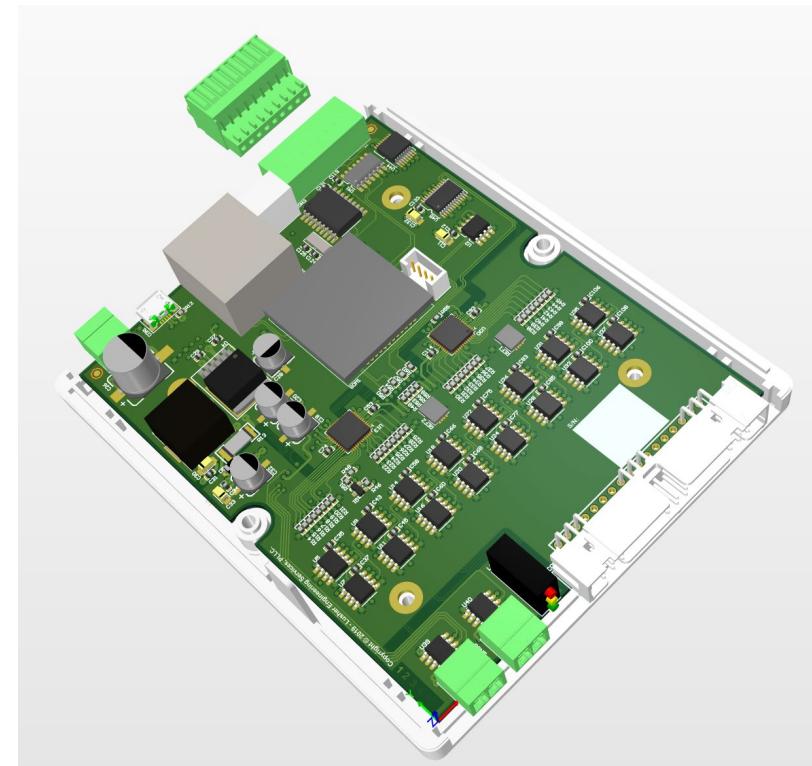
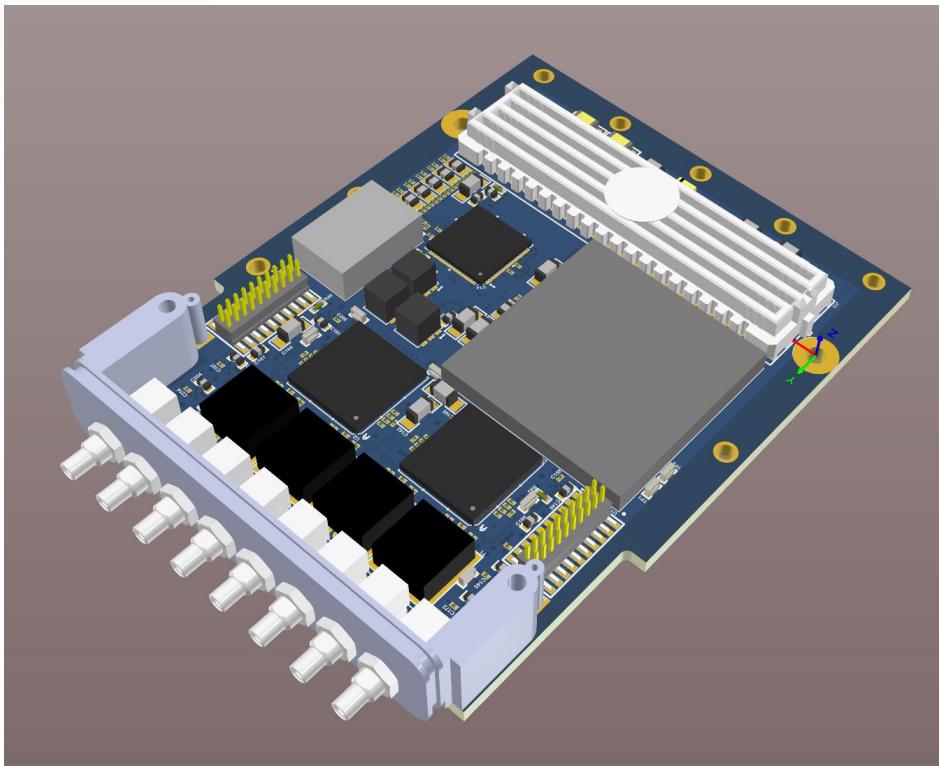
PCB Place and Route: Routing

- Layout is part an art form. Take your time. Care about what you are doing...



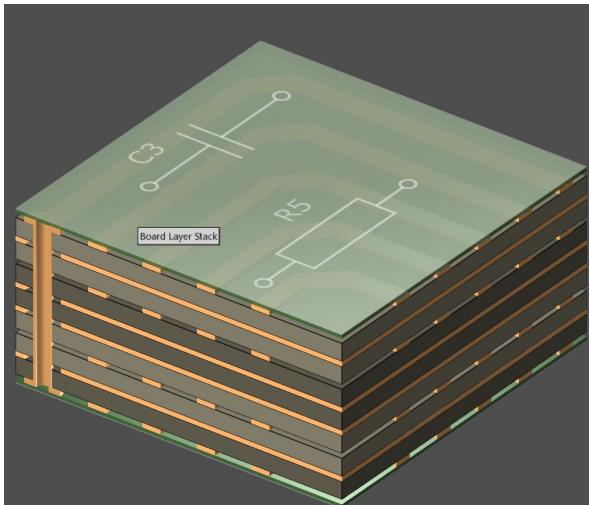
PCB Place and Route: Routing

- Some PCB editors will allow you to view your board in 3D, which can be useful when working with complicated mechanical features.

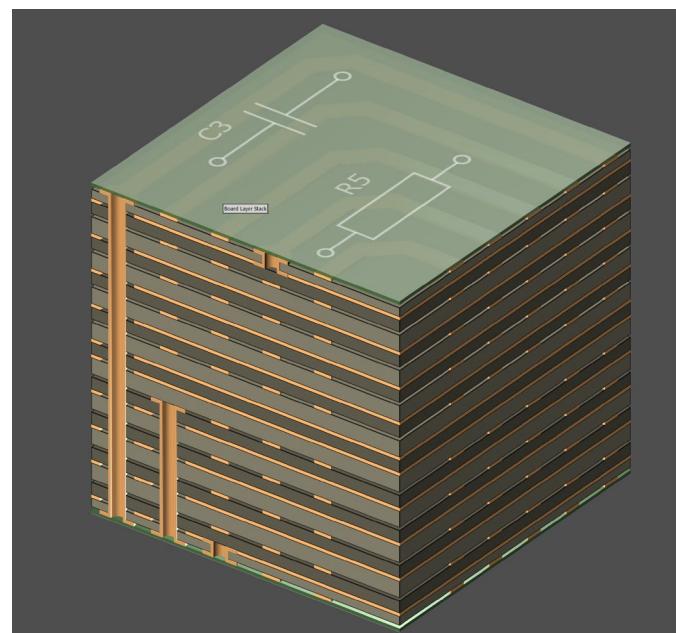


PCB Place and Route: Multi Layer PCBs

#	Name	Material	Type	Weight	Thickness	Dk	Df
	TopOverlay		Overlay				
	TopSolder	Solder Resist	Solder Mask		0.5mil	3.5	
1	TOP LAYER		Signal	1oz	1.7mil		
	Dielectric #1	FR-4	Prepreg		4mil	4.8	
2	GND PLANE		Plane	1oz	1.4mil		
	Dielectric 1	PP-006	Prepreg		2.8mil	4.1	0.02
3	MIDDLE LAYER #1	CF-004	Signal	1oz	1.378mil		
	Dielectric #2	FR-4	Prepreg		47mil	4.2	
4	MIDDLE LAYER #2	CF-004	Signal	1oz	1.378mil		
	Dielectric 2	PP-006	Prepreg		2.8mil	4.1	0.02
5	POWER PLANE		Plane	1oz	1.4mil		
	Dielectric #4	FR-4	Prepreg		4mil	4.2	
6	BOTTOM LAYER		Signal	1oz	1.7mil		
	BottomSolder	Solder Resist	Solder Mask		0.5mil	3.5	
	BottomOverlay		Overlay				



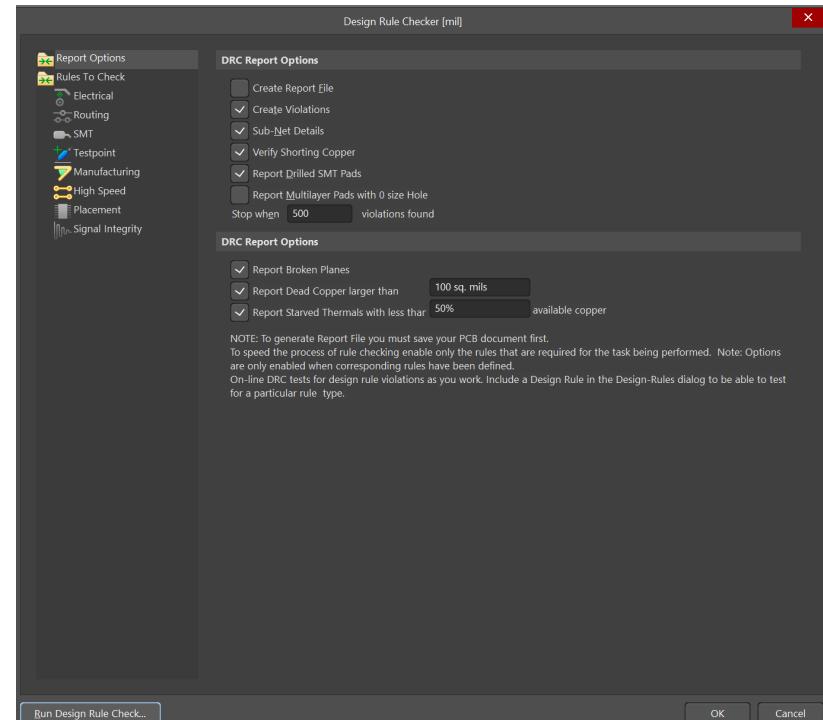
8-Layers



20-Layers
With blind and buried vias

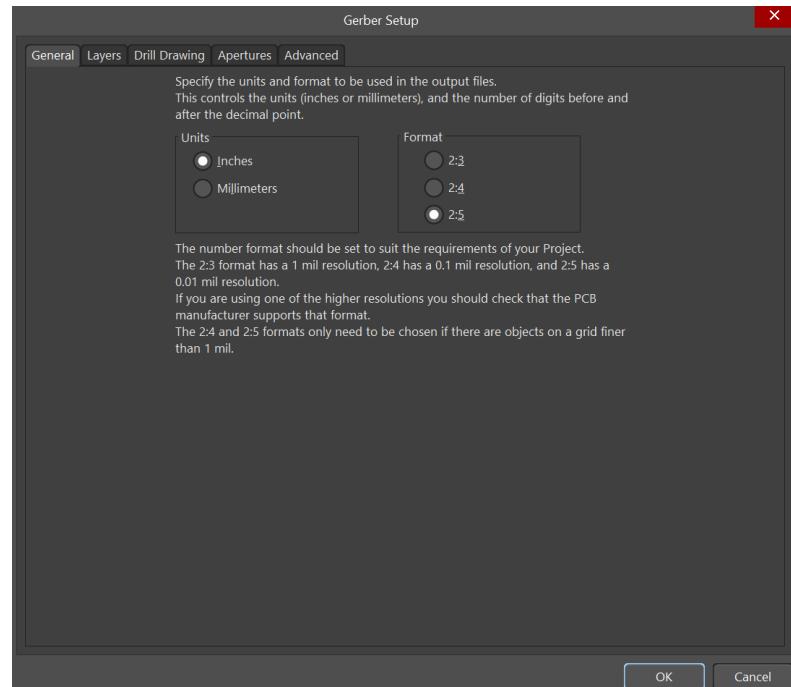
Perform a DRC Check

- If you fail the DRC, you must fix the errors!
 - The PCB manufacturer will not build it if it fails the DRC.
 - They will check against their own rule system.
 - Arguing with them is a waste of time! Just fix the issue.



PCB Place and Route: CAM

- You need to produce files that the manufacturer will use. This is not your design files.
- Minimum CAM Files include:
 - Gerber files
 - An ASCII Vector file format used in the creating the photo plot files for the layers.
 - NC Drill files



Recommend Software

- Professional Software Tools:
 - Altium Designer
 - Cadence OrCAD
 - Cadence Allegro PCB Designer
 - Mentor Graphics PADS

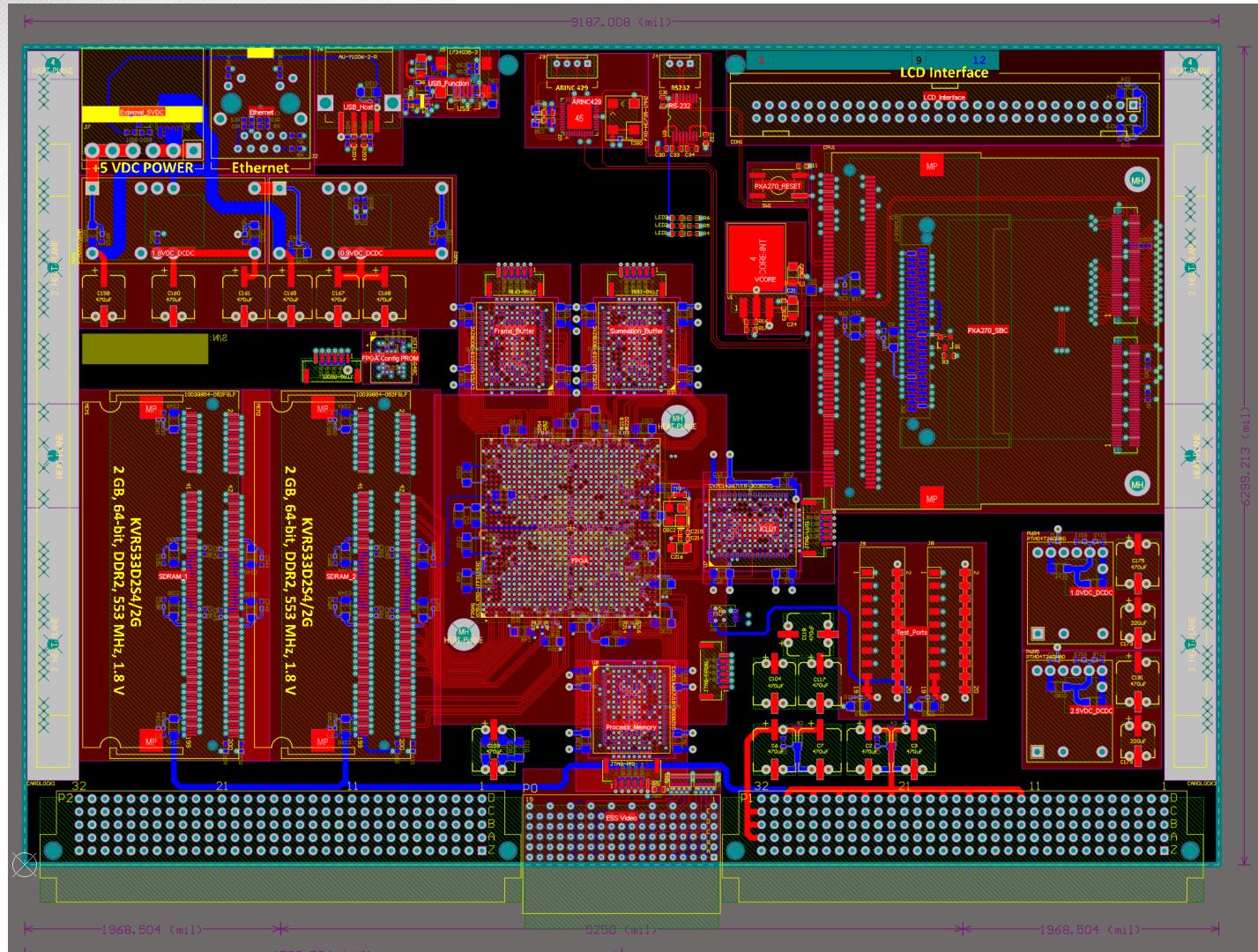
Common Mistakes

- Rushing the design.
- Not doing a design review.
- Trusting online symbols and footprints without verification.
- Using the auto router without setting up all of the design rules.

Common Mistakes

- Ignoring physics.
- Trace widths being too small.
- Hole sizes being too small.
- Not doing a practice PCB design first.
- Not caring about your job!

Questions on PCB Design?

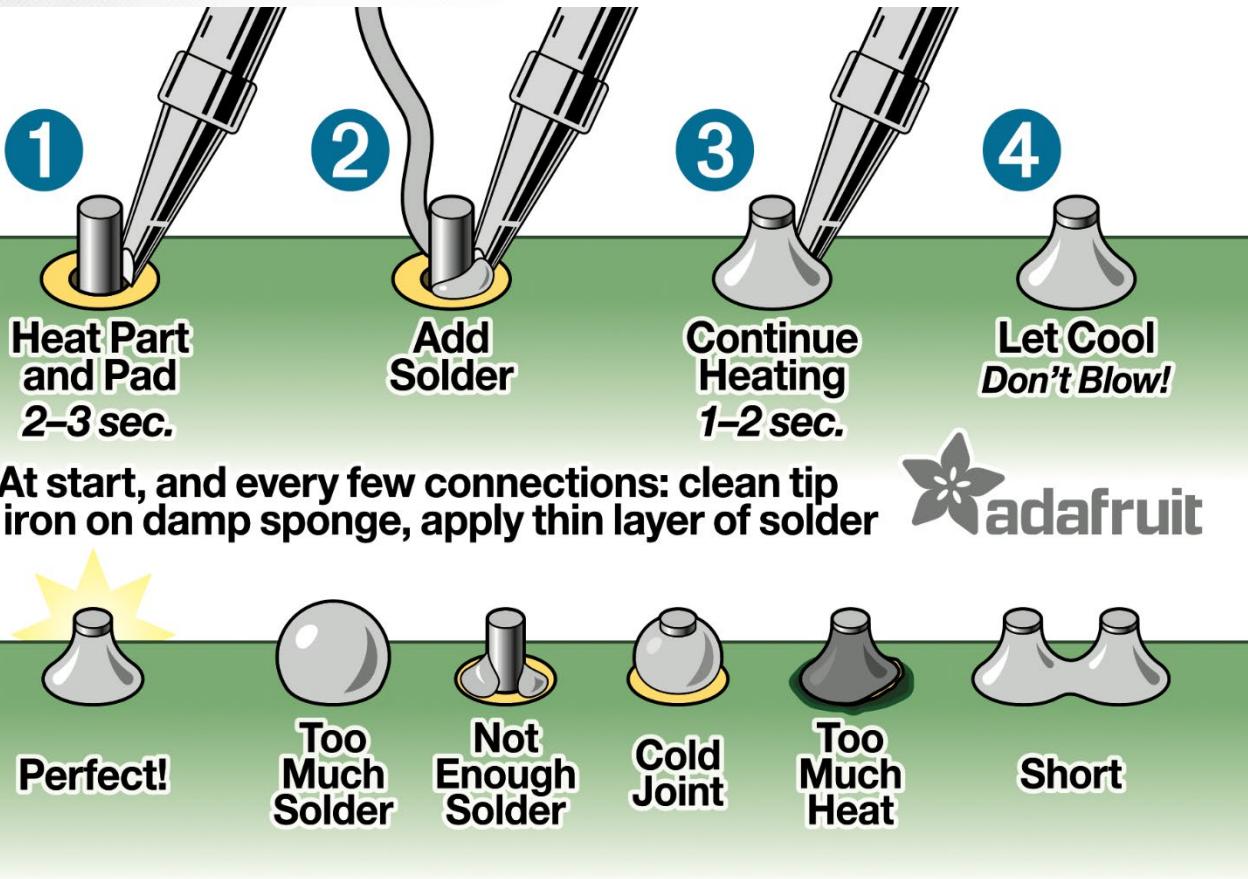


Assembly Tips

- Take your time! Do not rush assembly.
- Practice soldering with a practice board first.
- Start with the SMT ICs first, especially QFNs, TQFPs, etc..., then SMT devices, then finally all THT.

Assembly Tips

SOLDERING



Assembly Tips

- Use flux as necessary to make soldering easier. Most times flux in solder is sufficient for most joints.
- Purchase some extra parts, such as SMT caps and resistors and sometimes there is waste.



Assembly Tips

- Use the microscope in 113B for fine pitch parts. There are also various magnifying lenses that work as well.
- Print out your BOM and verify parts placement in the assembly drawing.



Assembly Tips

- You must clean your assembled PCB when done. No exceptions! Flux can be conductive and will cause circuit issue.
- Start with the SMT ICs first, especially QFNs, TQFPs, etc..., then rest of SMT devices, then finally all THT.